

# Preliminary Information

## NPN Silicon General Purpose Amplifier Transistor

This NPN transistor is designed for general purpose amplifier applications. This device is housed in the SOT-416/SC-90 package which is designed for low power surface mount applications, where board space is at a premium.

- Reduces Board Space
- High  $h_{FE}$ , 210–460 (typical)
- Low  $V_{CE(sat)}$ , < 0.5 V
- Available in 8 mm, 7-inch/3000 Unit Tape and Reel

### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ )

Rating	Symbol	Value	Unit
Collector-Base Voltage	$V_{(BR)CBO}$	50	Vdc
Collector-Emitter Voltage	$V_{(BR)CEO}$	50	Vdc
Emitter-Base Voltage	$V_{(BR)EBO}$	5.0	Vdc
Collector Current — Continuous	$I_C$	100	mAdc

### DEVICE MARKING

2SC4617 = B9

### THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation <sup>(1)</sup>	$P_D$	125	mW
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 ~ +150	$^\circ\text{C}$

### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	Min	Typ	Max	Unit
Collector-Base Breakdown Voltage ( $I_C = 50 \mu\text{Adc}$ , $I_E = 0$ )	$V_{(BR)CBO}$	50	—	—	Vdc
Collector-Emitter Breakdown Voltage ( $I_C = 1.0 \text{ mAdc}$ , $I_B = 0$ )	$V_{(BR)CEO}$	50	—	—	Vdc
Emitter-Base Breakdown Voltage ( $I_E = 50 \mu\text{Adc}$ , $I_C = 0$ )	$V_{(BR)EBO}$	5.0	—	—	Vdc
Collector-Base Cutoff Current ( $V_{CB} = 30 \text{ Vdc}$ , $I_E = 0$ )	$I_{CBO}$	—	—	0.5	$\mu\text{A}$
Emitter-Base Cutoff Current ( $V_{EB} = 4.0 \text{ Vdc}$ , $I_B = 0$ )	$I_{EBO}$	—	—	0.5	$\mu\text{A}$
Collector-Emitter Saturation Voltage <sup>(2)</sup> ( $I_C = 60 \text{ mAdc}$ , $I_B = 5.0 \text{ mAdc}$ )	$V_{CE(sat)}$	—	—	0.4	Vdc
DC Current Gain <sup>(2)</sup> ( $V_{CE} = 6.0 \text{ Vdc}$ , $I_C = 1.0 \text{ mAdc}$ )	$h_{FE}$	120	—	560	—
Transition Frequency ( $V_{CE} = 12 \text{ Vdc}$ , $I_C = 2.0 \text{ mAdc}$ , $f = 30 \text{ MHz}$ )	$f_T$	—	180	—	MHz
Output Capacitance ( $V_{CB} = 12 \text{ Vdc}$ , $I_C = 0 \text{ Adc}$ , $f = 1 \text{ MHz}$ )	$C_{OB}$	—	2.0	—	pF

1. Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.
2. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , D.C.  $\leq 2\%$ .

This document contains information on a product under development. Motorola reserves the right to change or discontinue this product without notice.

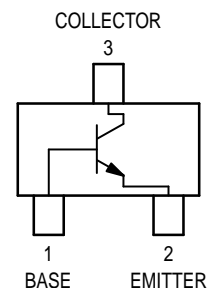
Thermal Clad is a trademark of the Bergquist Company

# 2SC4617

**NPN GENERAL  
PURPOSE AMPLIFIER  
TRANSISTORS  
SURFACE MOUNT**



**CASE 463-01, STYLE 1  
SOT-416/SC-90**



TYPICAL ELECTRICAL CHARACTERISTICS

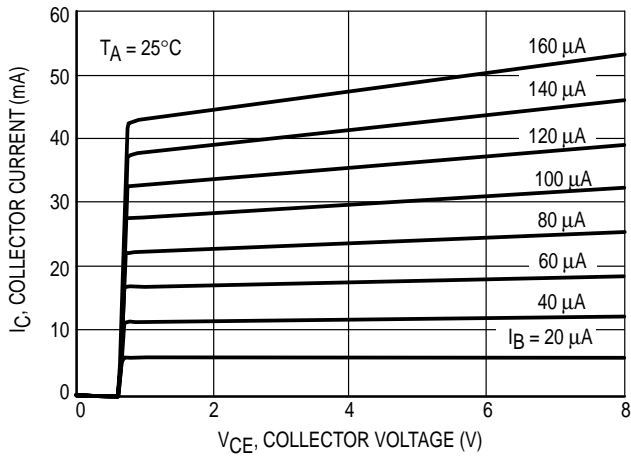


Figure 1.  $I_C - V_{CE}$

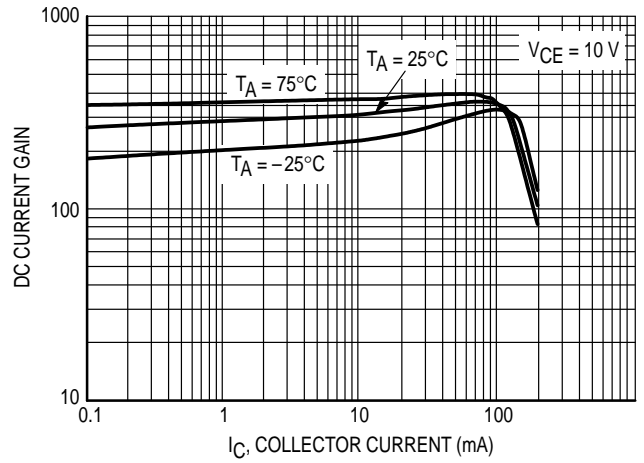


Figure 2. DC Current Gain

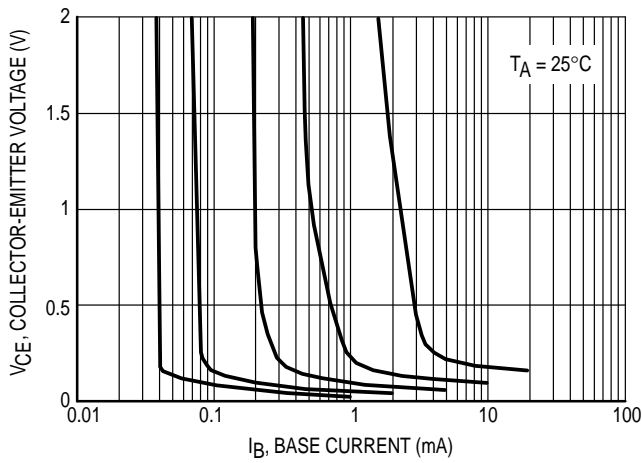


Figure 3. Collector Saturation Region

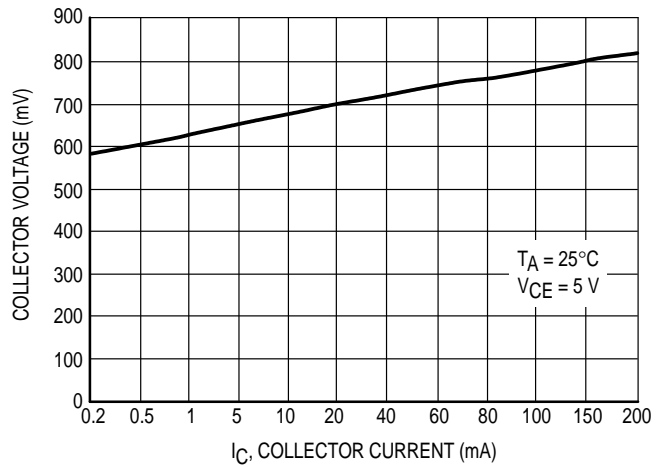


Figure 4. On Voltage

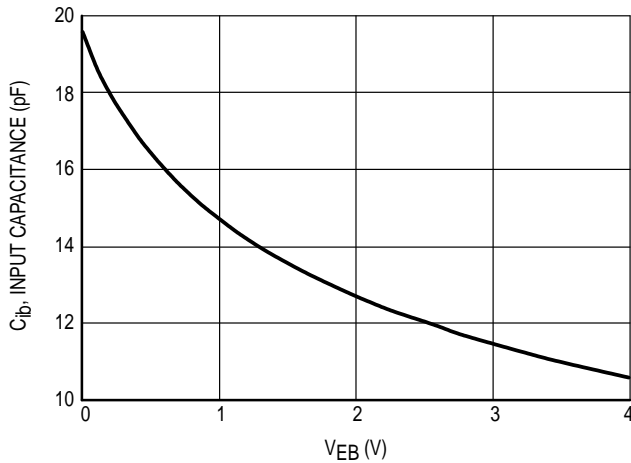


Figure 5. Capacitance

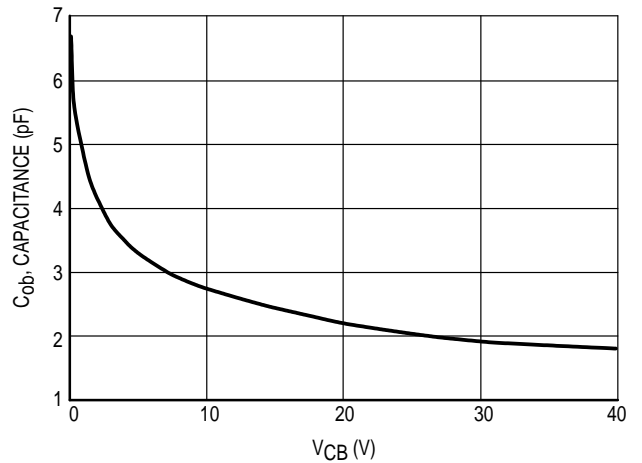


Figure 6. Capacitance



**SOLDER STENCIL GUIDELINES**

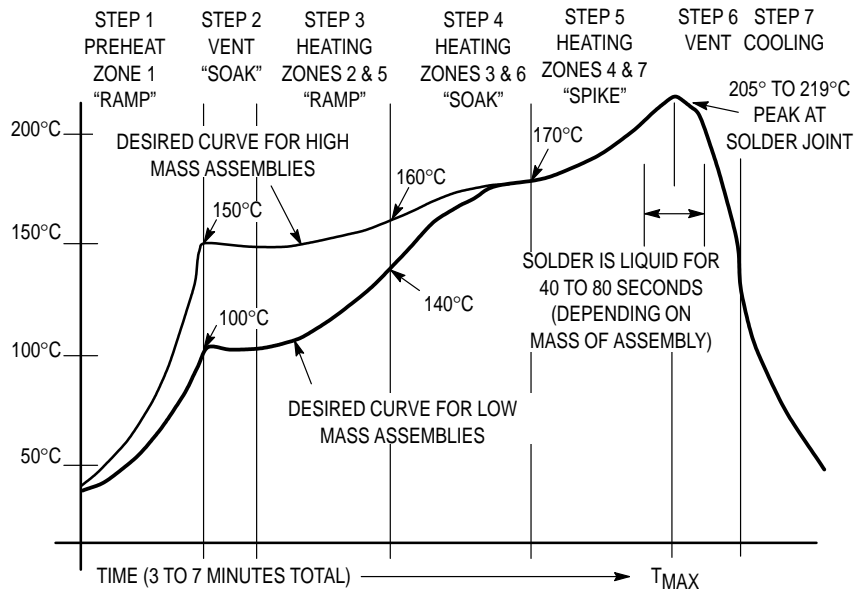
Prior to placing surface mount components onto a printed circuit board, solder paste must be applied to the pads. A solder stencil is required to screen the optimum amount of solder paste onto the footprint. The stencil is made of brass or stainless steel with a typical thickness of 0.008 inches.

The stencil opening size for the surface mounted package should be the same as the pad size on the printed circuit board, i.e., a 1:1 registration.

**TYPICAL SOLDER HEATING PROFILE**

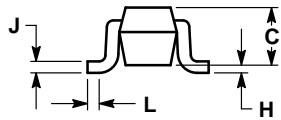
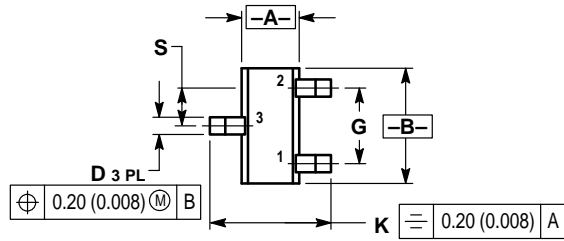
For any given circuit board, there will be a group of control settings that will give the desired heat pattern. The operator must set temperatures for several heating zones, and a figure for belt speed. Taken together, these control settings make up a heating "profile" for that particular circuit board. On machines controlled by a computer, the computer remembers these profiles from one operating session to the next. Figure 7 shows a typical heating profile for use when soldering a surface mount device to a printed circuit board. This profile will vary among soldering systems but it is a good starting point. Factors that can affect the profile include the type of soldering system in use, density and types of components on the board, type of solder used, and the type of board or substrate material being used. This profile shows temperature versus time. The line on the graph shows the

actual temperature that might be experienced on the surface of a test board at or near a central solder joint. The two profiles are based on a high density and a low density board. The Vitronics SMD310 convection/infrared reflow soldering system was used to generate this profile. The type of solder used was 62/36/2 Tin Lead Silver with a melting point between 177–189°C. When this type of furnace is used for solder reflow work, the circuit boards and solder joints tend to heat first. The components on the board are then heated by conduction. The circuit board, because it has a large surface area, absorbs the thermal energy more efficiently, then distributes this energy to the components. Because of this effect, the main body of a component may be up to 30 degrees cooler than the adjacent solder joints.



**Figure 7. Typical Solder Heating Profile**

PACKAGE DIMENSIONS



STYLE 1:  
 PIN 1. BASE  
 2. EMITTER  
 3. COLLECTOR

- NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: MILLIMETER.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.80	0.028	0.031
B	1.40	1.80	0.055	0.071
C	0.60	0.90	0.024	0.035
D	0.15	0.30	0.006	0.012
G	1.00 BSC		0.039 BSC	
H	—	0.10	—	0.004
J	0.10	0.25	0.004	0.010
K	1.45	1.75	0.057	0.069
L	0.10	0.20	0.004	0.008
S	0.50 BSC		0.020 BSC	

**CASE 463-01  
 ISSUE A  
 SOT-416/SC-90**

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